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Patent

AUG 22 2007

Customer No.: 31561  
Application No.: 10/711,540  
Docket No. 13365-US-PA

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant(s) : Ho et al.  
Application No. : 10/711,540  
Filed : September 24, 2004  
For : ELECTRICAL PACKAGE STRUCTURE INCLUDING  
CHIP WITH POLYMER THEREON  
Art Unit : 2818  
Examiner : NGUYEN, TRAM HOANG

**TRANSMITTAL LETTER**

**+1-571-273-8300**

**(Via fax: 1+2+8 pages)**

ASSISTANT COMMISSIONER FOR PATENTS  
Alexandria, VA 22314

Dear Sir,

In response to the Office Action dated May 7, 2007, please find the relevant papers in response thereof as follows:

- ☒ Request for Continued Examination in (2) pages;
- ☒ Preliminary Amendment in (8) pages.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date:

August 22, 2007

By:

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